

# **STPS1045**

# Power Schottky rectifier

## Main product characteristics

I <sub>F(AV)</sub>	10 A
V <sub>RRM</sub>	45 V
V <sub>F</sub>	0.57 V

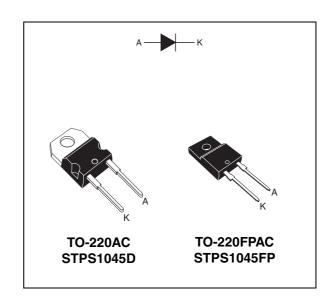
### **Features and Benefits**

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low forward voltage drop
- Insulated package: TO-220FPAC
  Insulating voltage = 2000V DC
  Capacitance = 12 pF
- Avalanche capability specified

### **Description**

Single chip Schottky rectifier suited for Switch Mode Power Supply and high frequency DC to DC converters.

This device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



STPS1045 **Characteristics** 

#### **Characteristics** 1

Table 1. **Absolute Ratings (limiting values)** 

Symbol	Parameter			Value	Unit
V <sub>RRM</sub>	Repetitive peak reverse voltage			45	V
I <sub>F(RMS)</sub>	RMS forward voltage			30	Α
	Average forward	TO-220AC	T <sub>c</sub> = 150° C	40	
$I_{F(AV)}$ current $\delta = 0.5$		TO-220FPAC	T <sub>c</sub> = 145° C	10	Α
I <sub>FSM</sub>	Surge non repetitive for	$t_p = 10 \text{ ms}$ sinusoidal	180	Α	
	Repetitive peak revers	t <sub>p</sub> = 2 μs F = 1 kHz	1	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p = 1 \mu s$ $C$			4000	W
T <sub>stg</sub>	Storage temperature range			-65 to + 175	°C
Tj	Maximum junction temperature			175	°C
dV/dt	Critical rate of rise of reverse voltage 100			10000	V/µs

#### Table 2. Thermal resistances

Symbol	Parameter		Value	Unit
B	Junction to case	TO-220AC	2.2	°C/W
R <sub>th(j-c)</sub>	ounction to case	TO-220FPAC	4.5	5/ ٧٧

Table 3. Static electrical characteristics

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup> Rev	Povorco logicado gurront	T <sub>j</sub> = 25° C	$V_R = V_{RRM}$			100	μΑ
'R`	I <sub>R</sub> <sup>(1)</sup> Reverse leakage current	T <sub>j</sub> = 125° C				15	mA
V <sub>F</sub> <sup>(2)</sup> Forward voltage drop		T <sub>j</sub> = 25° C	I <sub>F</sub> = 20 A			0.84	
	Forward voltage drop	T <sub>j</sub> = 125° C	I <sub>F</sub> = 20 A			0.72	V
		T <sub>j</sub> = 125° C	I <sub>F</sub> = 10 A			0.60	

<sup>1.</sup> Pulse test:  $tp = 5 \text{ ms}, \delta < 2\%$ 

To evaluate the conduction losses use the following equation: P = 0.42 x  $I_{F(AV)}$  + 0.015  $I_{F}^{2}_{(RMS)}$ 

$$P = 0.42 \times I_{F(AV)} + 0.015 I_{F^2(RMS)}$$

<sup>2.</sup> Pulse test: tp = 380  $\mu$ s,  $\delta$  < 2%

STPS1045 Characteristics

Figure 1. Average forward power dissipation Figure 2. Average forward current versus versus average forward current ambient temperature ( $\delta = 0.5$ )

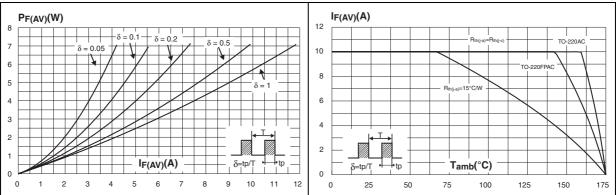


Figure 3. Normalized avalanche power derating versus pulse duration

Figure 4. Normalized avalanche power derating versus junction temperature

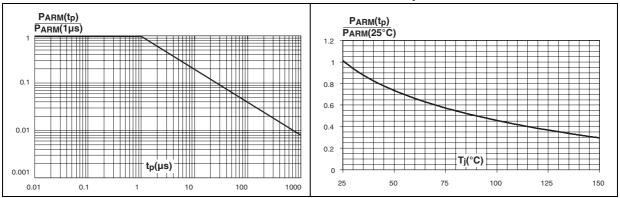
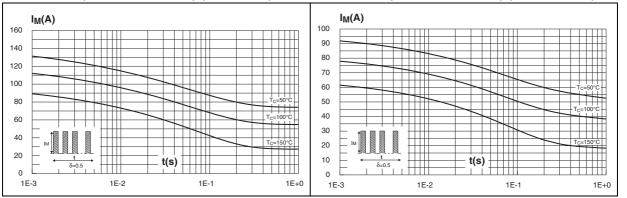


Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values) (TO-220AC)

Figure 6. Non repetitive surge peak forward current versus overload duration (maximum values) (TO-220FPAC)



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Figure 7. Relative variation of thermal transient impedance junction to case versus pulse duration (TO-220AC)

Figure 8. Relative variation of thermal transient impedance junction to case versus pulse duration (TO-220FPAC)

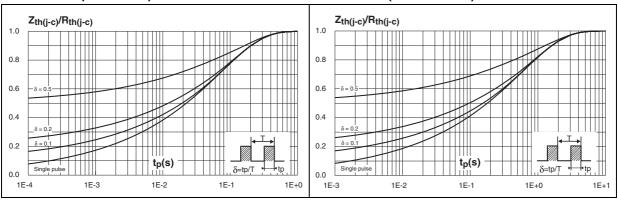


Figure 9. Reverse leakage current versus reverse voltage applied (typical values)

Figure 10. Reverse leakage current versus reverse voltage applied (typical values)

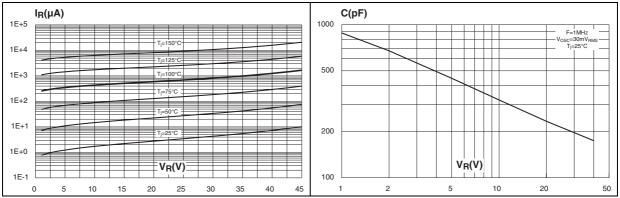
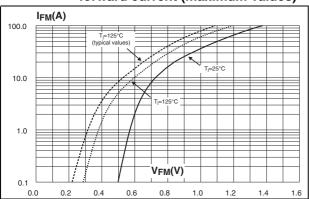


Figure 11. Forward voltage drop versus forward current (maximum values)



STPS1045 **Package Information** 

Inches

Max.

0.181

0.051

0.107

0.027

0.034

0.066

0.202

0.409

0.551

0.116

0.620

0.259

0.154

0.151

Min.

0.173

0.048

0.094

0.019

0.024

0.044

0.194

0.393

0.511

0.104

0.600

0.244

0.137

0.147

0.645 typ.

0.102 typ.

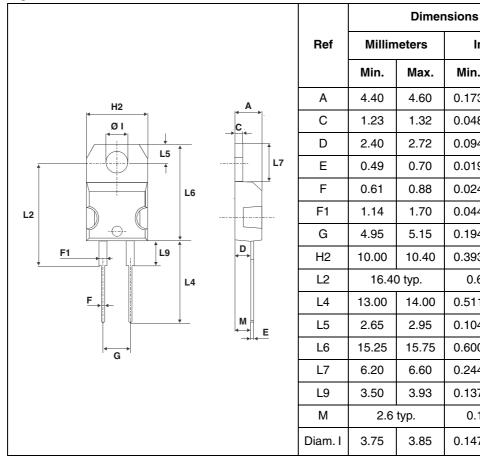
#### **Package Information** 2

Epoxy meets UL94, V0

Cooling method: by conduction (C) Recommended torque value: 0.55 Nm

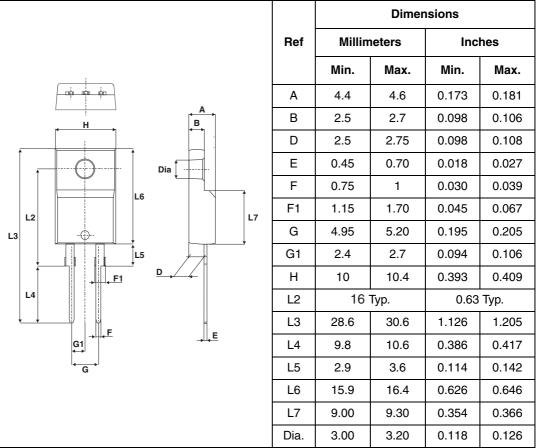
Maximum torque value: 0.70 Nm

Figure 12. TO-220AC dimensions



Package Information STPS1045

Figure 13. TO-220FPAC dimensions



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

# 3 Ordering Information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STPS1045D	STPS1045D	TO-220AC	1.86 g	50	Tube
STPS1045FP	STPS1045FP	TO-220FPAC	1.9 g	50	Tube

# 4 Revision history

Date	Revision	Description of Changes
Jul-2003	5D	Last release.
22-Mar-2007	6	Removed ISOWATT package.

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